MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

UQFN8 1.6X1.6, 0.5P
CASE 523AY
ISSUE O

DATE 31 AUG 2016

NOTES:
A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
B. DIMENSIONS ARE IN MILLIMETERS.
D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

SCALE: 2X

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